Is Now Part of

ON Semiconductor®

To learn more about ON Semiconductor, please visit our website at
www.onsemi.com

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (_), the underscore (_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at www.onsemi.com. Please email any questions regarding the system integration to Fairchild_questions@onsemi.com.

March 2015

FDD86110

N-Channel Shielded Gate PowerTrench® MOSFET

100 V, 50 A, 10.2 mΩ

Features

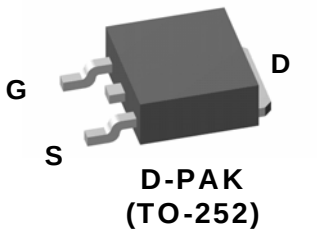
- Shielded Gate MOSFET Technology
- Max $r_{DS(on)}$ = 10.2 mΩ at V_{GS} = 10 V, I_D = 12.5 A
- Max $r_{DS(on)}$ = 16 mΩ at V_{GS} = 6 V, I_D = 9.8 A
- 100% UIL tested
- RoHS Compliant

General Description

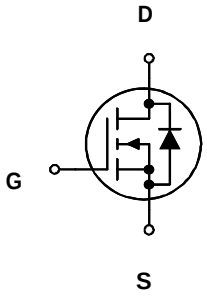
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench® process that incorporates Shielded Gate technology. This process has been optimized for the on-state resistance and yet maintain superior switching performance.

Application

- DC - DC Conversion



D-PAK
(TO-252)



MOSFET Maximum Ratings T_C = 25 °C unless otherwise noted

Symbol	Parameter			Ratings	Units
V_{DS}	Drain to Source Voltage			100	V
V_{GS}	Gate to Source Voltage			±20	V
I_D	Drain Current -Continuous	T_C = 25 °C		50	A
	-Continuous	T_A = 25 °C	(Note 1a)	12.5	
	-Pulsed		(Note 4)	150	
E_{AS}	Single Pulse Avalanche Energy		(Note 3)	135	mJ
P_D	Power Dissipation	T_C = 25 °C		127	W
	Power Dissipation	T_A = 25 °C	(Note 1a)	3.1	
T_J, T_{STG}	Operating and Storage Junction Temperature Range			-55 to +150	°C

Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	0.98	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	40	

Package Marking and Ordering Information

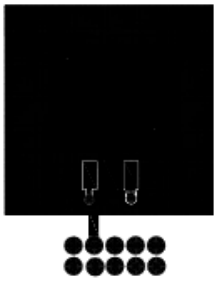
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD86110	FDD86110	D-PAK(TO-252)	13 ”	16 mm	2500 units

Electrical Characteristics T_J = 25 °C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain to Source Breakdown Voltage	I_D = 250 μA, V_{GS} = 0 V	100			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		72		mV/°C
I_{DSS}	Zero Gate Voltage Drain Current	V_{DS} = 80 V, V_{GS} = 0 V			1	μA
I_{GSS}	Gate to Source Leakage Current	V_{GS} = ±20 V, V_{DS} = 0 V			±100	nA
On Characteristics						
$V_{GS(th)}$	Gate to Source Threshold Voltage	V_{GS} = V_{DS}, I_D = 250 μA	2	2.8	4	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	I_D = 250 μA, referenced to 25 °C		-10		mV/°C
$r_{DS(on)}$	Static Drain to Source On Resistance	V_{GS} = 10 V, I_D = 12.5 A		8.5	10.2	mΩ
		V_{GS} = 6 V, I_D = 9.8 A		11.3	16	
		V_{GS} = 10 V, I_D = 12.5 A,T_J = 125°C		15	18	
g_{FS}	Forward Transconductance	V_{DS} = 10 V, I_D = 12.5 A		38		S
Dynamic Characteristics						
C_{iss}	Input Capacitance	V_{DS} = 50 V, V_{GS} = 0 V, f = 1MHz		1702	2265	pF
C_{oss}	Output Capacitance			379	505	pF
C_{rss}	Reverse Transfer Capacitance			17	30	pF
R_g	Gate Resistance		0.1	0.5	1.5	Ω
Switching Characteristics						
$t_{d(on)}$	Turn-On Delay Time	V_{DD} = 50 V, I_D = 12.5 A, V_{GS} = 10 V, R_{GEN} = 6 Ω		12	20	ns
t_r	Rise Time			5.4	10	ns
$t_{d(off)}$	Turn-Off Delay Time			19	35	ns
t_f	Fall Time			3.9	10	ns
Q_g	Total Gate Charge	V_{GS} = 0 V to 10 V; V_{DD} = 50 V, I_D = 12.5 A		25	35	nC
Q_{gs}	Gate to Source Charge			7.1		nC
Q_{gd}	Gate to Drain “Miller” Charge			5.2		nC
Drain-Source Diode Characteristics						
V_{SD}	Source-Drain Diode Forward Voltage	V_{GS} = 0 V, I_S = 12.5 A (Note 2)		0.80	1.3	V
		V_{GS} = 0 V, I_S = 2.6 A (Note 2)		0.72	1.2	
t_{rr}	Reverse Recovery Time	I_F = 12.5 A, di/dt = 100 A/μs		52	83	ns
Q_{rr}	Reverse Recovery Charge			60	96	nC

Notes:

1: $R_{\theta JA}$ is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta JA}$ is determined by the user's board design.



a) 40 °C/W when mounted on a 1 in^2 pad of 2 oz copper

b) 96 °C/W when mounted on a minimum pad

2: Pulse Test: Pulse Width < 300 μs, Duty cycle < 2.0%.

3: Starting T_J = 25 °C, L = 0.3 mH, I_{AS} = 30 A, V_{DD} = 90 V, V_{GS} = 10 V. 100% test at L = 0.1 mH, I_{AS} = 48 A.

4: Pulsed Drain current is tested at 300 μs with 2% duty cycle. For repetitive pulses, the pulse width is limited by the maximum junction temperature.

Typical Characteristics T_J = 25 °C unless otherwise noted

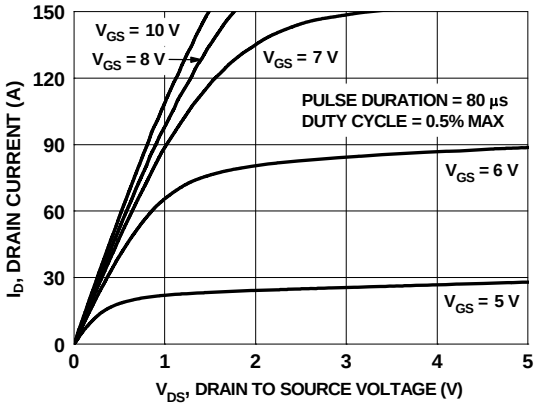


Figure 1. On Region Characteristics

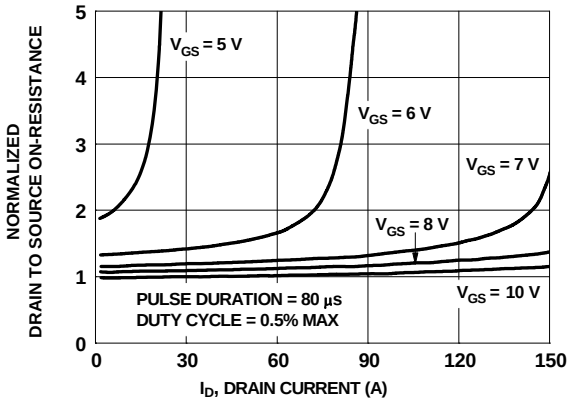


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

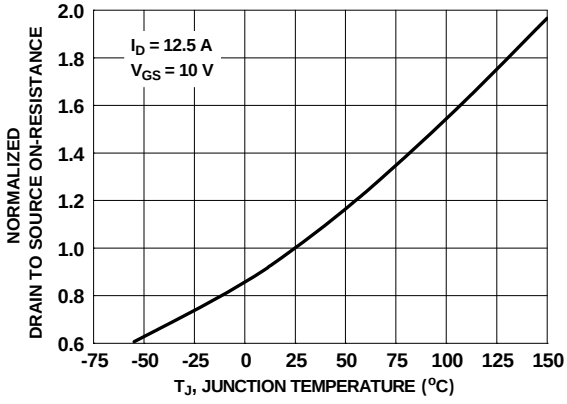


Figure 3. Normalized On Resistance vs Junction Temperature

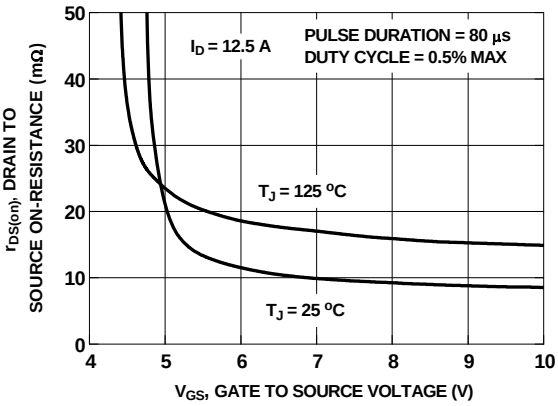


Figure 4. On-Resistance vs Gate to Source Voltage

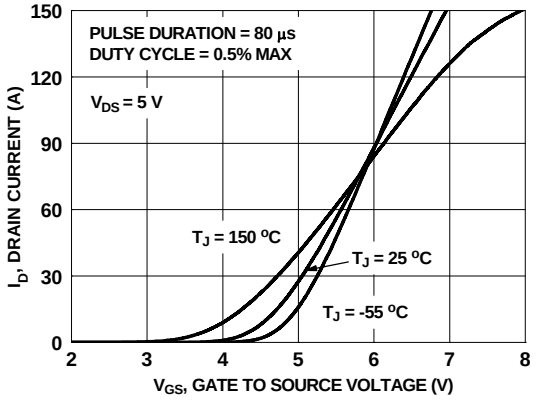


Figure 5. Transfer Characteristics

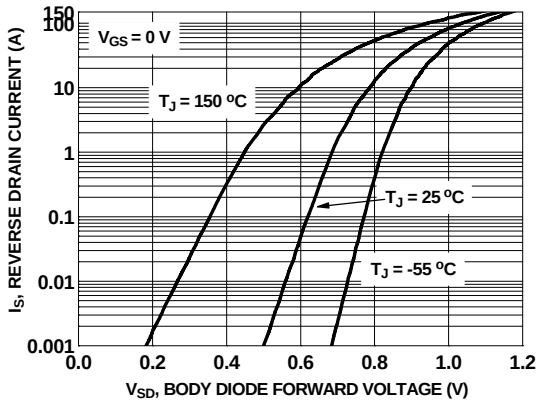


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

Typical Characteristics T_J = 25 °C unless otherwise noted

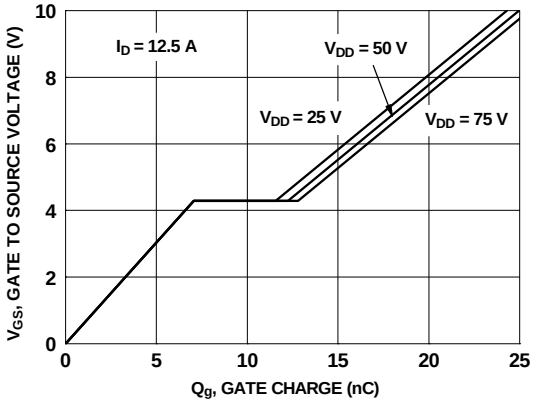


Figure 7. Gate Charge Characteristics

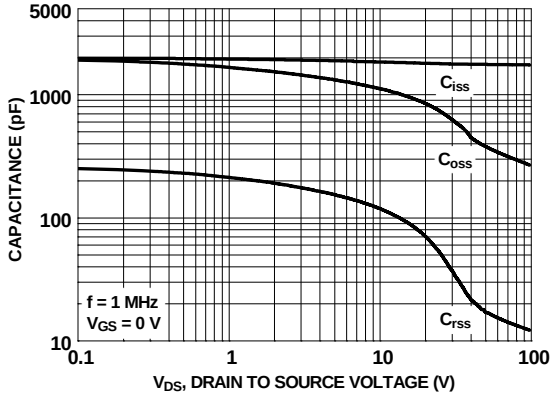


Figure 8. Capacitance vs Drain to Source Voltage

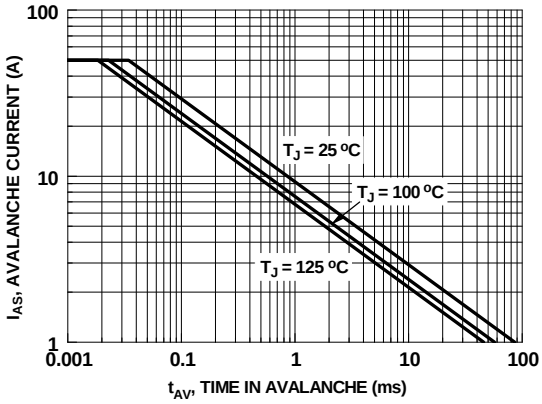


Figure 9. Unclamped Inductive Switching Capability

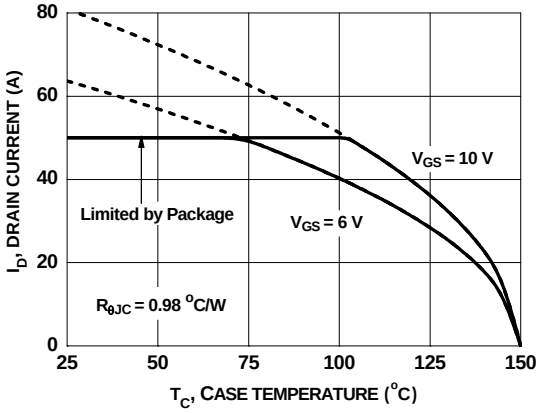


Figure 10. Maximum Continous Drain Current vs. Case Temperature

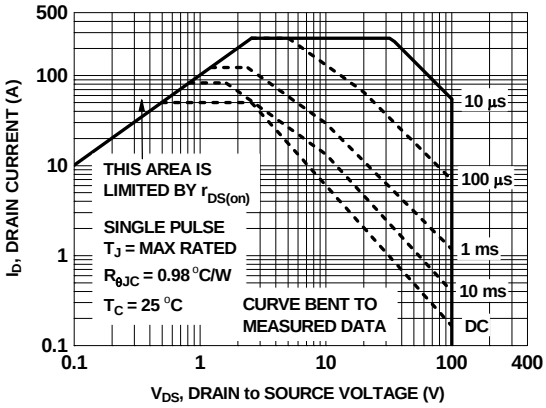


Figure 11. Forward Bias Safe Operating Area

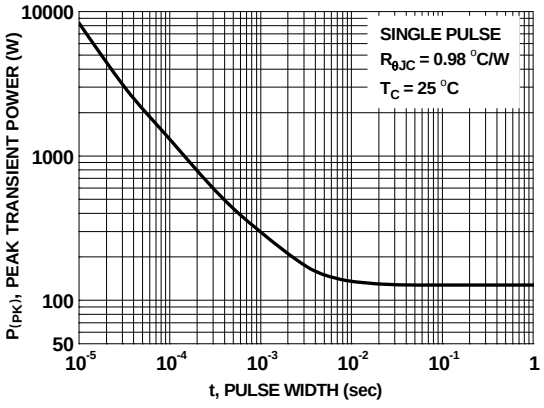


Figure 12. Single Pulse Maximum Power Dissipation

Typical Characteristics T_J = 25 °C unless otherwise noted

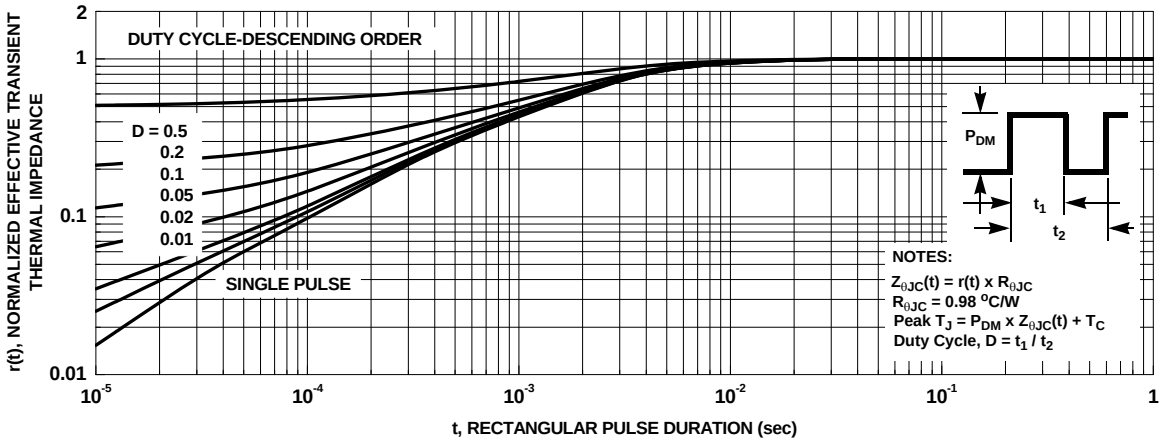
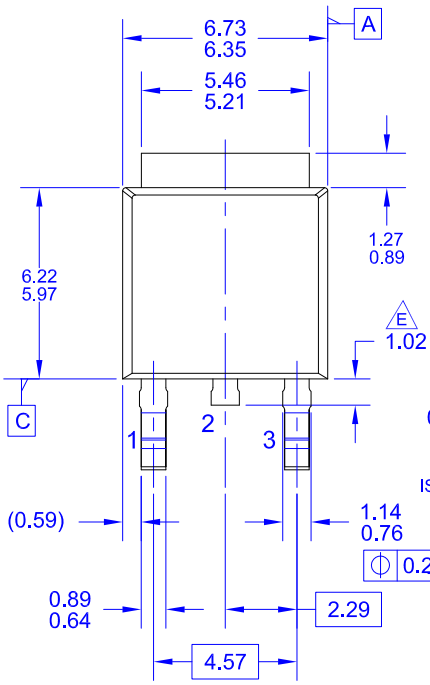
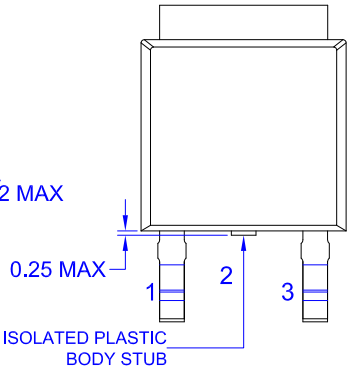


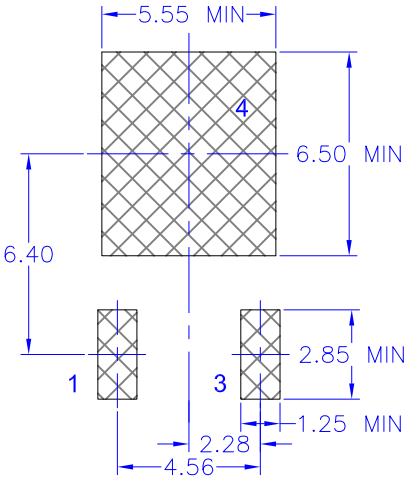
Figure 13. Junction-to-Case Transient Thermal Response Curve



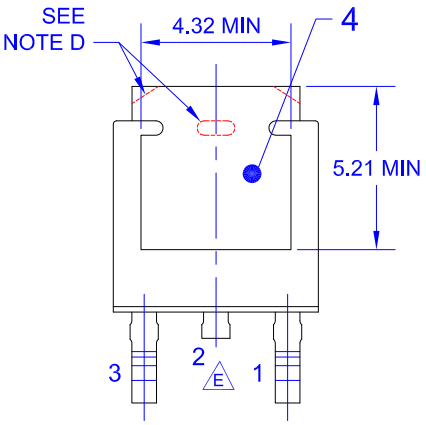
NON-DIODE PRODUCTS VERSION



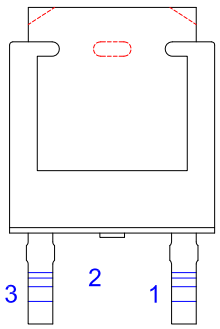
DIODE PRODUCTS VERSION



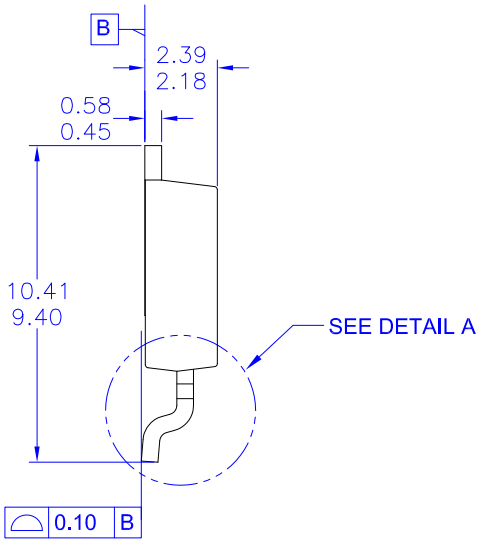
LAND PATTERN RECOMMENDATION



NON-DIODE PRODUCTS VERSION

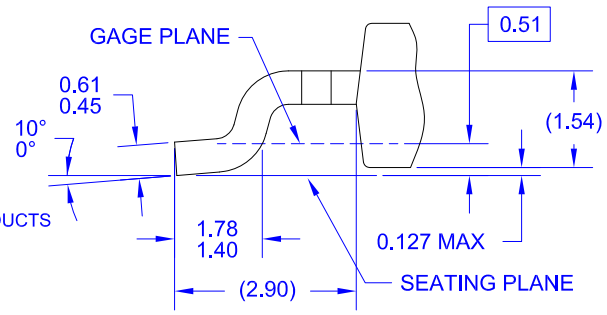


DIODE PRODUCTS VERSION



NOTES: UNLESS OTHERWISE SPECIFIED

A) THIS PACKAGE CONFORMS TO JEDEC, TO-252, ISSUE C, VARIATION AA.
B) ALL DIMENSIONS ARE IN MILLIMETERS.
C) DIMENSIONING AND TOLERANCING PER ASME Y14.5M-2009.
D) SUPPLIER DEPENDENT MOLD LOCKING HOLES OR CHAMFERED CORNERS OR EDGE PROTRUSION.
E) TRIMMED METAL CENTER LEAD IS PRESENT ON FOR NON-DIODE PRODUCTS
F) DIMENSIONS ARE EXCLUSIVE OF BURS, MOLD FLASH AND TIE BAR EXTRUSIONS.
G) LAND PATTERN RECOMMENDATION IS BASED ON IPC7351A STD TO228P991X239-3N.
H) DRAWING NUMBER AND REVISION: MKT-TO252A03REV11



DETAIL A
(ROTATED -90°)
SCALE: 12X

FAIRCHILD

PUBLICATION ORDERING INFORMATION

LITERATURE FULFILLMENT:
Literature Distribution Center for ON Semiconductor
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA
Phone: 303−675−2175 or 800−344−3860 Toll Free USA/Canada
Fax: 303−675−2176 or 800−344−3867 Toll Free USA/Canada
Email: orderlit@onsemi.com

N. American Technical Support: 800−282−9855 Toll Free USA/Canada
Europe, Middle East and Africa Technical Support:
Phone: 421 33 790 2910
Japan Customer Focus Center
Phone: 81−3−5817−1050

ON Semiconductor Website: **www.onsemi.com**

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative